

FEDL610Q772-01

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# ML610Q772

8-bit Microcontroller

#### GENERAL DESCRIPTION

This LSI is a high-performance 8-bit CMOS microcontroller into which rich peripheral circuits, such as timers, PWM, UART, I<sup>2</sup>C bus interface (master/slave), synchronous serial port, voltage level supervisor analog comparators and 10-bit successive approximation type A/D converter, are incorporated around 8-bit CPU nX-U8/100.

The CPU nX-U8/100 is capable of efficient instruction execution in 1-intruction 1-clock mode by pipe line architecture parallel processing. The Flash ROM that is installed as program memory, and the on-chip debug function that is installed, enable program debugging and programming on customer's board.

#### **FEATURES**

- CPU
  - 8-bit RISC CPU (CPU name: nX-U8/100)
  - Instruction system: 16-bit instructions
  - Instruction set:

Transfer, arithmetic operations, comparison, logic operations, multiplication/division, bit manipulations, bit logic operations, jump, conditional jump, call return stack manipulations, arithmetic shift, and so on

- On-Chip debug function
- Minimum instruction execution time:
  - •30.5us (@32.768kHz system clock)
  - •0.122us (@8.192MHz system clock)
- Internal memory
  - Flash memory:
    - Internal 32Kbyte Flash memory (16K x 16bit) for program including unusable 32byte test data area.
    - •Internal 4Kbyte Flash memory (2K x 16bit) for data.
  - SRAM memory:
    - Internal 4Kbyte data RAM (4K x 8bit)
  - Flash Memory operating condition and specification
    - Refer to the chapter Electrical characteristics "FLASH MEMORY SPECIFIACTION".
- Interrupt controller
  - 1 non-maskable interrupt source (Internal source: 1(WDT))
  - 30 maskable interrupt sources (Internal sources: 23, External source: 7)
- Time base counter (TBC)
  - Low-speed time base counter: 1 channel
  - High-speed time base counter: 1 channel
    - (This time base counter is divided by 1-16, and then it can be used as a clock of the Timer and PWM.)



#### • Watchdog timer (WDT)

- Non-maskable interrupt and reset
  - (Non-maskable interrupt is generated by the first overflow, and reset is generated by the second overflow)
- Free running
- Overflow period: 7 types selectable by software (23.4ms, 31.25ms, 62.5ms, 125ms, 500ms, 2s, and 8s)

#### Timer

- 8-bit x 6 channels (16-bit configuration available, 16-bit x 3ch)
- Supports auto reload timer mode/One shot timer mode
- Timer count start/stop by software or external input trigger
  - (Timer function with external trigger input supports for only 2ch. Selectable external pins/analog comparator output as an exeternal trigger.)
- The effective minimum pulse width of the external trigger input: Timer clock 3φ (about 183 ns @ 16.384 MHz)
- Allows measurement of pulse width etc. using an external trigger input.
- 8-selectable clock frequency as counter clock per channel

#### PWM

- Resolution 16-bit
- Single output x 3ch, Multiple three outputs x 1ch
- Allows an output of the PWM signal in a cycle of about 122ns (@PLLCLK = 16.384MHz) to 2s (@LSCLK = 32.768kHz)
- Supports one shot PWM mode
- PWM start/stop by software and external trigger input
  - (Selectable external pins, analog comparator output or timer interrupt as external trigger)
- 3-selectable clock frequency as PWM clock per channel

#### • UART

- TXD/RXD x 2ch
- Half-Duplex Communication
- Bit length, parity/no parity, odd parity/even parity, 1 stop bit/2 stop bits
- Positive logic/negative logic selectable
- Built-in baud rate generator

#### • I<sup>2</sup>C bus interface

- Master function: standard mode (100kbit/s@8MHz), Fast mode (400kbit/s@8MHz)
- Slave function : standard mode (100kbit/s)
- Synchronous serial port (SSIO)
  - 1ch
  - Master/slave selectable
  - LSB first/MSB first selectable
  - 8-bit length/16-bit length selectable
- Successive approximation type A/D converter (SA-ADC)
  - 10-bit A/D converter
  - 8ch Analog Input

#### Analog comparator

- 2ch
  - ch0: Allows comparison of the voltage level of the two external pins or comparison of one external pin and internal reference voltage level.
  - ch1: Allows comparison of one external pin and internal reference voltage level
- Input common mode voltage range :  $V_{DD} = 0.1 \text{V}$  to  $V_{DD} 1.5 \text{V}$
- Internal reference voltage: 0.1-0.8V (Selectable in 50mV increments)
- Hysteresis (Comparator only): 20mV(Typ.)
- Allows selection of with/without interrupt sampling and interrupt edge.

#### • General-purpose ports (GPIO)

25ch Input/output port

#### Reset

- Reset by the RESET N pin
- Reset by power-on detection
- Reset by the watchdog timer (WDT) 2nd overflow
- Reset by the voltage level supervisor (VLS) function: Selectable by software

#### Voltage level supervisor (VLS)

- 2ch
  - ·ch0: It can be used for voltage level detection reset
  - ·ch1: It can be used for voltage level detection interrupt
- Judgment accuracy: ±3.0% (Typ.)

#### Clock

- Low-speed clock:
  - Built-in RC oscillation (32.768kHz)
- High-speed clock:
  - Built-in PLL oscillation (16.384MHz)
  - · High-speed external clock (max. 8.192MHz)

Maximum CPU clock is 8.192MHz.

- Selection of high-speed clock mode by software:
  - · Built-in PLL oscillation
  - · External clock

#### Power management

- HALT mode: Instruction execution by CPU is suspended (peripheral circuits are in operating states)
- STOP mode: Stop of oscillation (Operations of CPU and peripheral circuits are stopped.)
- Clock gear: The frequency of system clock can be changed by software (1/1, 1/2, 1/4, or 1/8 of the oscillation clock).
- Block Control Function: Power down (reset registers and stop clock supply) the circuits of unused peripherals.

- Shipment
  - 32-pin LQFP: ML610Q772-xxxTC (xxx: code number)
- Guaranteed operating range
  - Operating temperature (ambience): -40°C to 105°C (Flash write/erase: -20°C to +85°C)
     Operating voltage: VDD=2.7V to 5.5V

#### **BLOCK DIAGRAM**

The block diagram is shown in figure 1.

<sup>&</sup>quot;\*" means secondary function, tertiary function or quaternary function of each port.

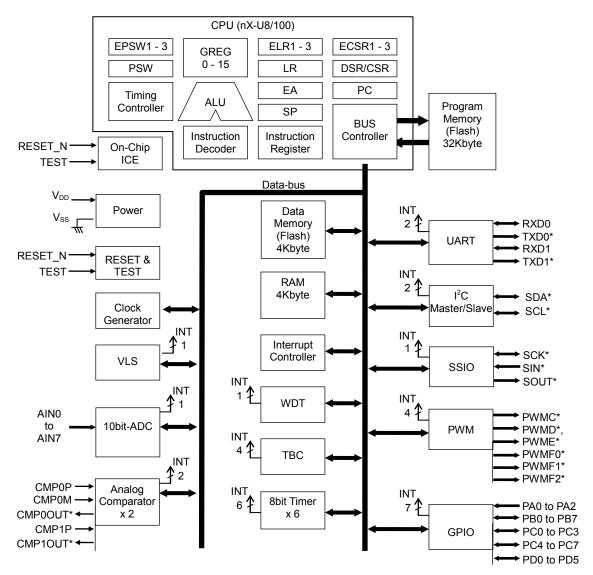


Figure 1. Block Diagram

### PIN CONFIGURATION (TOP VIEW)

The pin layout is shown in figure 2. PD5 L /TMFOUT /LSCLK / PWMD [: CMP1P / AIN1 / EXI1 / PA1 TESTF 9
PD2 10
TMFOUT / PC3 11
PD3 12
PD4 13
PD4 13
PWMF2 / PC2 14
PD5 15 PA2 / EXI2 / PWME / CLKIN / CMP0OUT TXD1/TXD0/SOUT/CMP0P/PB4 17 PB3 / EXI7 / SIN / TXD1 PWMF2 / SCL / SCK / RXD0 / CMP0M / PB5 6 PB2 / EXI6 / RXD1 / PWME PWMF1 / SDA / CLKIN / AIN4 / PB6 5 PB1 / EXI5 / AIN3 / PWMD / TXD0 / TXD1 4 Vss 3 PB0 / EXI4 / AIN2 / RXD0 / PWMC / OUTCLK / CMP1OUT  $V_{\text{DD}}$ 2 PD1 AIN7 / PC7 23 TEST PWMC / PWMF0 / LSCLK / RXD1 / AIN5 / PB7 PC5/SDA PC1/PWMF1 PD0 PA0 / EXI0 / AIN0 / PWMC PC6 / AIN6 / OUTCLK / TM9OUT PC4 / SCL PC0 / PWMF0 / TM9OUT

\* PIN No.3, 5-8, 16-19, 24, 25 can be used as external trigger of the Timer E-F and PWMC-F.

Figure 2. LQFP32 Pin Configuration

# **PIN LIST**

Table 1. Pin List

PIN No.	Primary function		nction	Secon	dary fi	ınction	Tert	iary fu	nction	Quaterna	ection	
111110.	Name	I/O		Name	I/O	Function	Name	I/O	Function	Name	I/O	function
21	$V_{SS}$	_	power supply		_	_	_	_	_	_	_	_
22	$V_{ m DD}$	_	power supply		_	_	_	-	_	_	_	_
9	TESTF	_	TEST	_	_	_	_	_	_	_	_	_
32	RESE T_N	I	SYSTEM	_	_	_	_	_	_	_	_	_
1	TEST	I/O	TEST		_	_	_	_	_	_	_	_
	PA0/		GPIO/									
	EXIO/		EXINT/					_				
25	AIN0/ TnTG*/	I/O	SA-ADC/	PWMC	О	PWM	OUTCLK	О	SYSTEM	TM9OUT	О	TIMER
	PmTG**		TIMER/ PWM									
	PA1/		GPIO/									
	EXI1/		EXINT/									
16	AIN1/	I/O	SA-ADC/	PWMD	О	PWM	LSCLK	0	SYSTEM	TMFOUT	О	TIMER
10	CMP1P/	1,0	COMP/	1 WIND		1 1111	Locali		SISILM	11111 001		THVIER
	TnTG*/ PmTG**		TIMER/ PWM									
-	PA2/		GPIO/									
0	EXI2/	1/0	EXINT/	DWAT		DWA	CLUDI	т	OVOTEM	CMDOOLIT		COMP
8	TnTG*/	I/O	TIMER/	PWME	О	PWM	CLKIN	I	SYSTEM	CMP0OUT	О	COMP
	PmTG**		PWM									
	PBO/		GPIO/ EXINT/									
	EXI4/ AIN2/		SA-ADC/									
3	RXD0/	I/O	UART/	PWMC	О	PWM	OUTCLK	О	SYSTEM	CMP1OUT	О	COMP
	TnTG*/		TIMER/									
	PmTG**		PWM									
	PB1/		GPIO/									
5	EXI5/ AIN3/	I/O	EXINT/ SA-ADC/	PWMD	О	PWM	TXD0	О	UART	TXD1	О	UART
3	TnTG*/	1/0	TIMER/	1 WIND		1 1111	TABO		OTHE	TADI		OTHE
	PmTG**		PWM									
	PB2/		GPIO/									
	EXI6/	1/0	EXINT/	DWAT					_   _		_	
6	RXD1/ TnTG*/	I/O	UART/ TIMER/	PWME	О	PWM	_			_		
	PmTG**		PWM									
	PB3/		GPIO/									
7	EXI7/	I/O	EXINT/	SIN	I	SSIO	TXD1	О	UART			_
,	TnTG*/	1/0	TIMER/	Silv	1	5510	IADI		UAICI			
	PmTG** PB4/		PWM GPIO/									
17	CMP0P	I/O	COMP	SOUT	О	SSIO	TXD0	О	UART	TXD1	О	UART
	PB5/		GPIO/				1					
18	RXD0/	I/O	UART/	SCK	I/O	SSIO	SCL	I/O	I <sup>2</sup> C	PWMF2	О	PWM
	CMP0M		COMP									
19	PB6/	I/O	GPIO/	CLKIN	I	SYSTEM	SDA	I/O	I <sup>2</sup> C	PWMF1	О	PWM
-	AIN4 PB7/		SA-ADC GPIO/									
24	AIN5/	I/O	SA-ADC/	LSCLK	О	SYSTEM	PWMF0	О	PWM	PWMC	0	PWM
	RXD1		UART									
30	PC0	I/O	GPIO		_	_	PWMF0	О	PWM	TM9OUT	О	TIMER
27	PC1	I/O	GPIO	_	_	_	PWMF1	О	PWM	_	_	_
14	PC2	I/O	GPIO		_	_	PWMF2	О	PWM	_	_	_
11	PC3	I/O	GPIO		_	_	_	_	_	TMFOUT	О	TIMER
		<u> </u>				ı.			T.			

PIN No.						inction					ary function	
	Name	I/O	Function	Name	I/O	Function	Name	I/O	Function	Name	I/O	function
29	PC4	I/O	GPIO	SCL	I/O	I <sup>2</sup> C	_	_	_	_	_	_
28	PC5	I/O	GPIO	SDA	I/O	I <sup>2</sup> C	_	_			_	_
26	PC6/ AIN6	I/O	GPIO/ SA-ADC	_	_	_	_	_	_	_	_	_
23	PC7/ AIN7	I/O	GPIO/ SA-ADC	_	_	_	_	_	_	_	_	_
31	PD0	I/O	GPIO/	_	_	_	_	_		_	_	_
2	PD1	I/O	GPIO/	_	_	_		_	_	_	_	_
10	PD2	I/O	GPIO	_	_	_	_	_	_	_	_	_
12	PD3	I/O	GPIO	_	_	_	_	_	_	_	_	_
13	PD4	I/O	GPIO	_	_	_	_	_	_	_	_	_
15	PD5	I/O	GPIO	_	_	_	_	_	_	_	_	_

<sup>\* :</sup> TnTG = TETG, TFTG.

<sup>\*\*:</sup> PmTG = PCTG, PDTG, PETG, PFTG.

# PIN DESCRIPTION

**Table 2. Pin Description** 

	1			
Pin name	I/O	Description	Primary Secondary Tertiary, Quaternary	Logic
System				
RESET_N	I	Reset input pin. When this pin is set to "L" level, system reset mode is set and the internal section is initialized. When this pin is set to "H" level subsequently, program execution starts. A pull-up resistor is internally connected.	Primary	Negative
CLKIN	I	High-speed clock input pin. This pin is used as the secondary function of PB6 pin and also as the tertiary function of PA2 pin.	Secondary, Tertiary	_
LSCLK	О	Low-speed clock output pin. This pin is used as the secondary function of PB7 pin and also as the tertiary function of the PA1.	Secondary, Tertiary	_
OUTCLK	О	High-speed clock output pin. This pin is used as the tertiary function of the PA0 and PB0 pin.	Tertiary	
General Purpos	e Input	/Output Port		
PA0 to PA2 PB0 to PB7 PC0 to PC7 PD0 to PD5	I/O	General-purpose input/output port. Since these pins have secondary, tertiary or quaternary functions, the pins cannot be used as a port when the secondary, tertiary or quaternary functions are used.	Primary	Positive
Synchronous S	erial I/C			
SIN	I	Synchronous serial data input pin. This pin is used as the secondary function of PB3 pin.	Secondary	Positive
SCK	I/O	Synchronous serial clock input/output pin. This pin is used as the secondary function of PB5 pin.	Secondary	
SOUT	О	Synchronous serial data output pin. This pin is used as the secondary function of PB4 pin.	Secondary	Positive
UART				
TXD0	0	UART0 data output pin. This pin is used as the tertiary function of the PB1 and PB4 pin.	Tertiary	Positive
RXD0	I	UARTO data input pin. This pin is used as the primary function of the PBO and PB5 pin	Primary	Positive
TXD1	О	UART1 data output pin. This pin is used as the tertiary function of the PB3 pin and also the quaternary function of the PB1 and PB4 pin.	Tertiary Quaternary	Positive
RXD1	I	UART1 data input pin. This pin is used as the primary function of the PB2 and PB7 pin.	Primary	Positive
I <sup>2</sup> C Bus Interfa	ce			
SCL	I/O	Serial clock input/output. This pin is used as the tertiary function of the PB5 and the secondary function of the PC4 pin.	Tertiary Secondary	Positive
SDA	I/O	Serial data input/output. This pin is used as the tertiary function of the PB6 and the secondary function of the PC5 pin.	Tertiary Secondary	Positive
PWM				
PWMC	О	PWMC output pin. This pin is used as the secondary function of the PA0 and PB0 and also the quaternary function of the PB7 pin.	Secondary Quaternary	Positive/ Negative
PWMD	О	PWMD output pin. This pin is used as the secondary function of the PA1 and PB1 pin.	Secondary	Positive/ Negative
PWME	О	PWME output pin. This pin is used as the secondary function of the PA2 and PB2 pin.	Secondary	Positive/ Negative
PWMF0	О	PWMF0 output pin. This pin is used as the tertiary function of the PB7 and PC0 pin.	Tertiary	Positive/ Negative
PWMF1	О	PWMF1 output pin. This pin is used as the tertiary function of the PC1 and also the quaternary function of PB6 pin.	Tertiary/ Quaternary	Positive/ Negative
		4-merens of the control of the contr	( """ )	- 118

DUD (E2		PWMF2 output pin. This pin is used as the tertiary function of the PC2 and also the	Tertiary/	Positive/
PWMF2	О	quaternary function of the PB5 pin.	Quaternary	Negative
Pin name	I/O	Description	Primary Secondary Tertiary, Quaternary	Logic
External Interru	pt	<u>,                                      </u>		
EXI0 to 2	I	External maskable interrupt input pins. Interrupt enable and edge selection can be performed for each bit by software. These pins are used as the primary functions of the $PAO - PA2$ pins.	Primary	Positive/ negative
EXI4 to 7	I	External maskable interrupt input pins. Interrupt enable and edge selection can be performed for each bit by software. These pins are used as the primary functions of the PB0 – PB3 pins.	Primary	Positive/ negative
Timer				
TETE, TFTG	I	External clock input pin used for both Timer E and Timer F. These pins are used as the primary function of the PA0-PA2, PB0-PB7 pins.	Primary	_
TM9OUT	О	Timer 9 output pin. This pin is used as the quaternary function of the PA0 and PC0 pin.	Quaternary	Positive
TMFOUT	О	Timer F output pin. This pin is used as the quaternary function of the PA1 and PC3 pin.	Quaternary	Positive
Successive appr	oximat	ion type A/D converter		_
AIN0	I	Channel 0 analog input for successive approximation type A/D converter. This pin is used as the primary function of the PA0 pin.	Primary	_
AIN1	I	Channel 1 analog input for successive approximation type A/D converter. This pin is used as the primary function of the PA1 pin.	Primary	_
AIN2	I	Channel 2 analog input for successive approximation type A/D converter. This pin is used as the primary function of the PB0 pin.	Primary	_
AIN3	I	Channel 3 analog input for successive approximation type A/D converter. This pin is used as the primary function of the PB1 pin.	Primary	_
AIN4	I	Channel 4 analog input for successive approximation type A/D converter. This pin is used as the primary function of the PB6 pin.	Primary	_
AIN5	I	Channel 5 analog input for successive approximation type A/D converter. This pin is used as the primary function of the PB7 pin.	Primary	_
AIN6	I	Channel 6 analog input for successive approximation type A/D converter. This pin is used as the primary function of the PC6 pin.	Primary	_
AIN7	I	Channel 7 analog input for successive approximation type A/D converter. This pin is used as the primary function of the PC7 pin.	Primary	_
Comparator				
CMP0P	I	Non-inverting input for comparator0. This pin is used as the primary function of the PB4 pin.	Primary	_
CMP0M	I	Inverting input for comparator 0. This pin is used as the primary function of the PB5 pin.	Primary	_
CMP0OUT	О	Output for comparator 0. This pin is used as the quaternary function of the PA2 pin.	Quaternary	_
CMP1P	I	Non-inverting input for comparator 1. This pin is used as the primary function of the PA1 pin.	Primary	_
CMP1OUT	О	Output for comparator 1. This pin is used as the quaternary function of the PB0 pin.	Quaternary	_
TEST		1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		
TEST	I/O	Input/output pin for testing. A pull-down resistor is internally connected.		Positive
TESTF	1/0	Test pin for flash memory. A pull-down resistor is internally connected.		1 0511176
		rest pin for hash memory. A pun-down resistor is internany connected.		
Power Supply	1	Negativa navar gundy nin		
$\frac{V_{SS}}{V}$	<del>  -</del>	Negative power supply pin.	_	
$V_{ m DD}$		Positive power supply pin.	_	

#### TERMINATION OF UNUSED PINS

Table 3 shows methods of terminating the unused pins for ML610Q772

**Table 3. Termination of Unused Pins** 

Pin	Recommended pin termination
RESET_N	Open
TEST	Open
TESTF	Open
PA0 to PA2	Open
PB0 to PB7	Open
PC0 to PC7	Open
PD0 to PD5	Open
N.C.	Open

### Note:

It is recommended to set the unused input ports and input/output ports to the inputs with pull-down resistors/pull-up resistors or the output mode since the supply current may become excessively large if the pins are left open in the high impedance input setting.

#### **ELECTRICAL CHARACTERISTICS**

#### ABSOLUTE MAXIMUM RATINGS

(V<sub>SS</sub>=0V)

Parameter	Symbol	Condition	Rating	Unit
Power supply voltage	$V_{DD}$	Ta = 25°C	-0.3 to +7.0	V
Input voltage	V <sub>IN</sub>	Ta = 25°C	-0.3 to V <sub>DD</sub> +0.3	V
Output voltage	V <sub>OUT</sub>	Ta = 25°C	-0.3 to V <sub>DD</sub> +0.3	V
Output current	I <sub>OUT</sub>	Ta = 25°C	-12 to +11	mA
Power dissipation	PD	Ta = 25°C	0.84	W
Storage temperature	T <sub>STG</sub>	_	-55 to 150	°C

### RECOMMENDED OPERATING CONDITIONS

 $(V_{SS}=0V)$ 

Parameter	Symbol	Condition	Range	Unit
Operating temperature (ambience)	T <sub>OP</sub>	_	-40 to +105	°C
Operating voltage	$V_{DD}$	_	2.7 to 5.5	V

### • FLASH MEMORY SPECIFICATION

(V<sub>SS</sub>= 0V)

				( • 55 –	
Parameter	Symbol	Condition	Rating	Unit	
Operating temperature	_	At read	-40 to +105	°C	
(ambience)	$T_{OPF}$	At write/erase	-20 to +85	°C	
Rewrite counts*1	C <sub>EPD</sub>	Data flash memory (4KB)	6000	cycles	
Rewrite Courts	$C_{EPP}$	Program flash memory	80	Cycles	
	_	Chip-erase	Program flash and Data flash memory	_	
	_	Block-erase (Program flash memory)	8	KB	
Erase unit	_	Block-erase (Data flash memory)	4	KB	
	_	Sector-erase (Data flash memory)	1	KB	
Erase time (max.)	_	Chip-erase/Block-erase/Sector-erase	100	ms	
Write unit			1word(2bytes)	_	
Write time (max.)	_	1word(2bytes)	40	μS	
Data retention*2	$Y_{DR}$	_	15	years	

<sup>\*1:</sup> Rewrite count is counted as one even if you suspend erase operation.

In addition, following capability of Flash memory is available;

 $<sup>^{\</sup>star 2}\!\!:$  However, keep active time of the LSI from exceeding ten years.

<sup>-</sup> security function: providing security ID for the protection of program code implemented in Flash memory

<sup>-</sup> accidental-write protection: providing special sequence to protect accidental write data to Flash memory. By writing "0FAx" and "0F5x" sequentially, before write/erase, writing one word is available just only one time.

<sup>-</sup> erase interrupt function: in the case of external interrupt during erasing flash memory, erase execution is suspended. And then the interrupt is activated. Please re-erase after interrupt execution.

### DC CHARACTERISTICS (Supply Current)

( $V_{DD}$ =2.7 to 5.5V,  $V_{SS}$ =0V,  $T_a$ =-40 to +105°C, unless otherwise specified)

		0 1111		Rating		Linit	Measuring	
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	circuit	
Supply current 1	IDD1	CPU : In STOP state (All clock stop) V <sub>DD</sub> =5.0V	_	1	50	μА		
Supply current 2	IDD2	CPU : In HALT state* <sup>1</sup> (Only CR oscillation operates) V <sub>DD</sub> =5.0V	_	240	_	μА		
Supply current 3	IDD3	CPU: CR32.768kHz operating state* <sup>2</sup> (Only CR oscillation operates) V <sub>DD</sub> =5.0V	_	250	_	μА	1	
Supply current 4	IDD4	CPU: CR8.192MHz operating state*3 (CR and PLL oscillation operate) VDD=5.0V	_	4	6	mA		

<sup>\*1:</sup> LTBC and WDT are operating ,and significant bits of BLKCON0 to BLKCON7 registers are all "1".

\*2: When the CPU operating rate is 100%. Minimum instruction execution time: Approx 30.52 μs (at 32.768kHz system clock)

\*3: When the CPU operating rate is 100%. Minimum instruction execution time: Approx 122 ns (at 8.192MHz system clock)

# • DC CHARACTERISTICS (VLS, Comparator)

(V<sub>DD</sub>=2.7 to 5.5V, V<sub>SS</sub>=0V, T<sub>a</sub>=-40 to +105°C, unless otherwise specified)

			· · · · · · · · · · · · · · · · · · ·	, v <sub>SS</sub> -0v,	Rating	. 100 O, um		wise specified) Measuring		
Parameter	Symbol	Condition	1	Min.	Тур.	Max.	Unit	circuit		
VLS0 threshold voltage	V <sub>VLS0F</sub>	Ta=25°C		Typ -3.0%	2.85	Typ +3.0%				
(V <sub>DD</sub> =fall)	V VLS0F	_		Typ -5.0%	2.03	Typ +5.0%				
VLS0 threshold voltage	V <sub>VLS0R</sub>	Ta=25°C	Typ -3.0%	2.92	Typ +3.0%					
(V <sub>DD</sub> =rise)	V VLSOR	_	Typ -5.0%	2.92	Typ +5.0%					
			VLS1=0		3.3		V			
VLS1 threshold voltage		Ta=25°C	VLS1=1	Тур	3.6	Тур				
	V <sub>VLS1</sub>	1a-25 C	VLS1=2	-3.0%	3.9	+3.0%				
			VLS1=3		4.2					
(V <sub>DD</sub> =fall)	V VLS1		VLS1=0	Тур	3.3			1		
( 55 - )			VLS1=1		3.6	Тур		·		
		_	VLS1=2	-5.0%	3.9	+5.0%				
			VLS1=3		4.2					
Comparator0 In-phase input voltage range	V <sub>CMR</sub>	_		0.1	_	V <sub>DD</sub> -1.5	V			
Comparator0	.,	Ta=25°C , V <sub>DD</sub> :	= 5.0V	10	20	30				
hysteresis	V <sub>HYSP</sub>	V <sub>DD</sub> = 5.0\	/	5	20	35				
Comparator0 Input offset voltage	V <sub>CMOF</sub>	Ta=25°C , V <sub>DD</sub> = 5.0V			_	7	mV			
Comparator		Ta=25°C		-25	_	25				
Reference- voltage error*1	V <sub>CMREF</sub>	_	- Ta=25°C			50				

<sup>\*1 :</sup> Comparator input offset voltage is included.

# • DC CHARACTERISTICS (IO pins)

(V<sub>DD</sub>=2.7 to 5.5V, V<sub>SS</sub>=0V,  $T_a$ =-40 to +105° $\underline{C}$ , unless otherwise specified)

-		(VDD-2.7 to 3.	5v, v <sub>SS</sub> -0v,	Rating	100 C, un	icss other	Measuring	
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	circuit	
	VOH1	IOH=-3.0mA, V <sub>DD</sub> =4.5V* <sup>1</sup> Ta= -40 to 85°C	V <sub>DD</sub> -0.7	_	_			
Output voltage1 ( TEST,	VOITI	IOH=-3.0mA, V <sub>DD</sub> =4.5V* <sup>1</sup>	V <sub>DD</sub> -0.8	_	_			
PA0-2, PB0-7, PC0-7, PD0-5)	VOL1	IOL=+8.5mA, V <sub>DD</sub> =4.5V* <sup>1</sup> Ta= -40 to 85°C	_	_	0.6	V	2	
	VOLT	IOL=+8.5mA, V <sub>DD</sub> =4.5V* <sup>1</sup>	_	_	0.7			
Output voltage2 (PB5, PB6 PC4, PC5)	VOL2	IOL=+3.0mA	_	_	0.4			
Output leakage ( PA0-2, PB0-7,	ЮОН	VOH = V <sub>DD</sub> (in high-impedance state)	_	_	1	- μΑ	3	
PC0-7, PD0-5)	IOOL	VOL = V <sub>SS</sub> (in high-impedance state)	-1	_	1	μν		
Input current 1	IIH1	VIH1 = V <sub>DD</sub>	_	_	1			
(RESET_N)	IIL1	VIL1 = V <sub>SS</sub> , V <sub>DD</sub> = 5.0V	-650	-500	-350			
Input current 2	IIH2	VIH2= V <sub>DD</sub> = 5.0V	20	115	200			
(TEST)	IIL2	VIL2 = V <sub>SS</sub>	-1	_	1	μА	4	
	IIH3	VIH3 = $V_{DD}$ = 5.0V (when pulled-down)	20	115	200	μΑ	4	
Input current 3 (PA0-2, PB0-7,	IIL3	VIL3 = $V_{SS}$ , $V_{DD}$ = 5.0V (when pulled-up)	-200	-100	-20			
PC0-7, PD0-5)	IIH3Z	VIH3 = V <sub>DD</sub> (in high-impedance stat)	_	_	1			
	IIL3Z	VIH3 = V <sub>SS</sub> (in high-impedance stat)	-1	_	_			

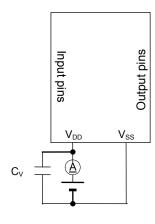
<sup>\*1:</sup> When the one terminal output state.

(V<sub>DD</sub>=2.7 to 5.5V, V<sub>SS</sub>=0V, T<sub>a</sub>=-40 to +105°C, unless otherwise specified)

		(188 2.1 60 0.1		Rating			Measuring	
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	circuit	
Input voltage 1 ( RESET_N, TEST,	VIH1	-	0.7 ×V <sub>DD</sub>	_	$V_{DD}$	V	2	
PA0-2, PB0-7, PC0-7, PD0-5)	VIL1	-	0	_	0.3 ×V <sub>DD</sub>		2	
Input pin capacitance ( PA0-2, PB0-7, PC0-7, PD0-5 )	CIN	f = 10kHz Ta = 25°C	_	_	20	pF	_	

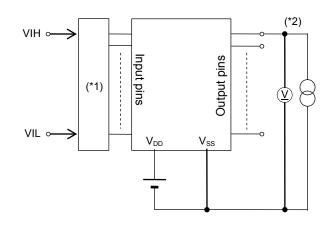
### MEASURING CIRCUITS

### Measuring circuit 1

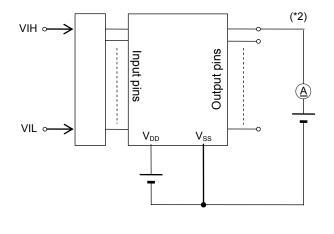


 $C_V$ :  $1\mu F$ 

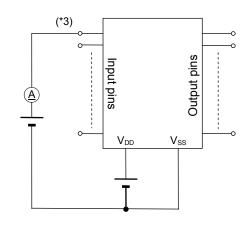
# Measuring circuit 2



### Measuring circuit 3



### Measuring circuit 4



- \*1: Input logic circuit to determine the specified measuring conditions.
- \*2: Measured at the specified output pins.
- \*3: Measured at the specified input pins.

### AC CHARACTERISTICS (Clock)

( $V_{DD}$ =2.7 to 5.5V,  $V_{SS}$ =0V,  $T_a$ =-40 to +105°C, unless otherwise specified)

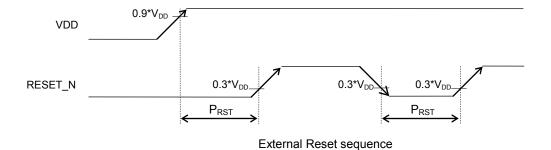
Dovernator	Cy made al	Condition		Rating		Unit	
Parameter	Symbol	Condition	Min.	Typ. Max.		Unit	
32kHz RC oscillation frequency*2		Ta = -20 to 85°C	Typ. -3%	00.700	Typ. +3%	kHz	
	f <sub>RCL</sub>	_	Typ. -4%	32.768	Typ. +4%		
PLL oscillation frequency *1*2		Ta = -20 to 85°C	Typ. -3%	40.004	Typ. +3%	NAL I	
	f <sub>PLL</sub>	_	Typ. -4%	16.384	Typ. +4%	MHz	

 $<sup>^{\</sup>star 1}$ : 1024 clock average. Maximum CPU clock frequency is  $f_{PLL}/2$ .  $^{\star 2}$ : Guaranteed value at the factory shipment.

### AC CHARACTERISTICS (Power on / Reset sequence)

( $V_{DD}$ =2.7 to 5.5V,  $V_{SS}$ =0V,  $T_a$ =-40 to +105°C, unless otherwise specified)

		( 55				'
Parameter	Curahal	Rating			l lmit	
	Symbol	Condition	Min.	Тур.	Max.	Unit
Reset pulse width	P <sub>RST</sub>	_	100	_	_	
Reset noise elimination pulse width	P <sub>NRST</sub>	_	_	_	0.4	μS
Power-on reset activation power rise tilt	⊿V/⊿T	0V → 2.0V	0.10	_	10	V/ms



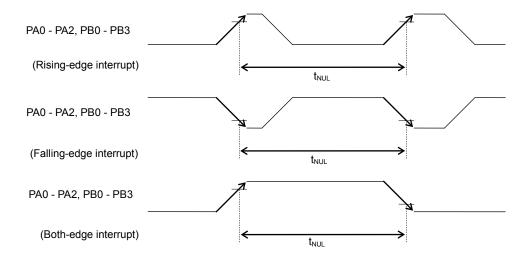


Power-on Reset sequence

# • AC CHARACTERISTICS (External Interrupt)

( $V_{DD}$ =2.7 to 5.5V,  $V_{SS}$ =0V,  $T_a$ =-40 to +105°C, unless otherwise specified)

Dovernatar	Curah al	Condition	Rating			Limit
Parameter 	Symbol	Condition	Min.	Тур.	Max.	Unit
External interrupt disable period	T <sub>NUL</sub>	Interrupt: Enabled (MIE = 1), CPU: NOP operation	2.5 x sysclk	_	3.5 x sysclk	φ

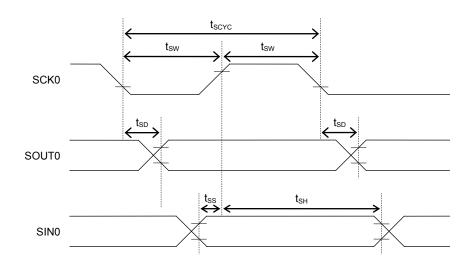


# • AC CHARACTERISTICS (Synchronous Serial Port)

( $V_{DD}$ =2.7 to 5.5V,  $V_{SS}$ =0V,  $T_a$ =-40 to +105°C, unless otherwise specified)

		, ==	Condition   Rating   Min.   Typ.   M		00 011101 11100	<u> </u>
Parameter	Symbol	Condition			Max.	Unit
SCK input cycle	4	When high-speed oscillation is not active	10	_	_	μS
(slave mode)	tscyc	When high-speed oscillation is active	500	_	_	ns
SCKoutput cycle (master mode)	t <sub>scyc</sub>	_	_	SCK*1	_	s
SCK input pulse width	+	When high-speed oscillation is not active	4	_	_	μS
(slave mode)	t <sub>SW</sub>	When high-speed oscillation is active	200	_	_	ns
SCK output pulse width (master mode)	t <sub>SW</sub>	_	t <sub>scyc</sub> ×0.4	t <sub>scyc</sub> ×0.5	t <sub>scyc</sub> ×0.6	s
SOUT output delay (slave mode)	t <sub>SD</sub>	_	_	_	180	ns
SOUT output delay (master mode)	t <sub>SD</sub>	_	_	_	80	ns
SIN input setup time (slave mode)	t <sub>ss</sub>	_	50	_	_	ns
SIN input hold time	t <sub>SH</sub>	—	50	_	_	ns

<sup>\*1:</sup> Clock period selected with S0CK3-0 of the serial port 0 mode register(SIO0MOD1)



• AC CHARACTERISTICS (I<sup>2</sup>C Bus Interface: Standard Mode 100kHz)

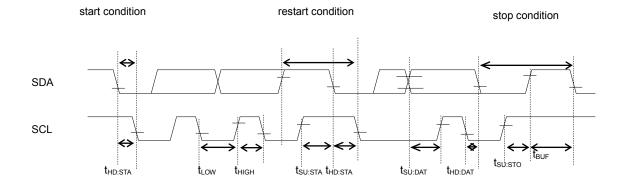
( $V_{DD}$ =2.7 to 5.5V,  $V_{SS}$ =0V,  $T_a$ =-40 to +105°C, unless otherwise specified)

Doromotor	Cymahal	Condition	Rating		I Imia		
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	
SCL clock frequency	f <sub>SCL</sub>	_	0	_	100	kHz	
SCL hold time (start/restart condition)	t <sub>HD:STA</sub>	_	4.0	_	_	μS	
SCL"L" level time	t <sub>LOW</sub>	_	4.7	_	_	μS	
SCL"H" level time	t <sub>HIGH</sub>	_	4.0	_	_	μS	
SCL setup time (restart condition)	t <sub>SU:STA</sub>	_	4.7	_	_	μS	
SDA hold time	t <sub>HD:DAT</sub>	_	0	_	_	μS	
SDA setup time	t <sub>SU:DAT</sub>	_	0.25	_	_	μS	
SCL setup time (stop condition)	t <sub>su:sto</sub>	_	4.0	_	_	μS	
Bus-free time	t <sub>BUF</sub>	_	4.7	_	_	μS	

• AC CHARACTERISTICS (I<sup>2</sup>C Bus Interface: Fast Mode 400kHz)

(V<sub>DD</sub>=2.7 to 5.5V, V<sub>SS</sub>=0V, Ta=-40 to +105°C, unless otherwise specified)

		(100 2:1 10 0:01, 133 01, 14 1	0 10 .00	Rating		- p - c
Doromotor	Cymhol	Condition		I Imia		
Parameter	Symbol	Symbol Condition		Тур.	Max.	Unit
SCL clock frequency	f <sub>SCL</sub>	_	0	_	400	kHz
SCL hold time (start/restart condition)	t <sub>HD:STA</sub>	_	0.6	_	_	μS
SCL"L" level time	t <sub>LOW</sub>	_	1.3	_		μS
SCL"H" level time	t <sub>HIGH</sub>	_	0.6	_	_	μS
SCL setup time (restart condition)	t <sub>SU:STA</sub>	_	0.6	_	_	μS
SDA hold time	t <sub>HD:DAT</sub>	_	0	_	_	μS
SDA setup time	t <sub>SU:DAT</sub>	_	0.1	_	_	μS
SCL setup time (stop condition)	t <sub>su:sto</sub>	_	0.6	_	_	μS
Bus-free time	t <sub>BUF</sub>	_	1.3	_	_	μS

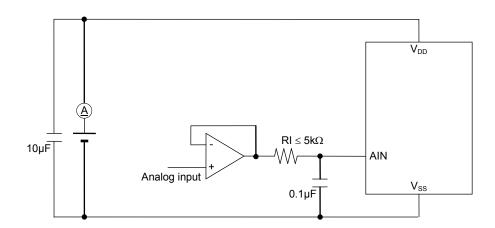


• Electrical Characteristics of Successive Approximation Type A/D Converter

(V<sub>DD</sub>=2.7 to 5.5V, V<sub>SS</sub>=0V,  $T_a$ =-40 to +105°C, unless otherwise specified)

		( ==		•		<u> </u>	
Doromotor	Cumbal	Condition		Rating	Rating		
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	
Resolution	n	_	_	_	10	bit	
Integral non-linearity error	INL	_	-4	_	+4		
Differential non-linearity	DNL		-3		+3		
error	DINL	_	-3		73	LSB	
Zero-scale error	$V_{OFF}$	_	-4	_	+4		
Full-scale error	FSE	_	-4	_	+4		
Conversion time	t <sub>CONV</sub>	_	_	102	_	φ/CH	

Φ : period of OSCLK (more than 3MHz)



#### PACKAGE DIMENSIONS

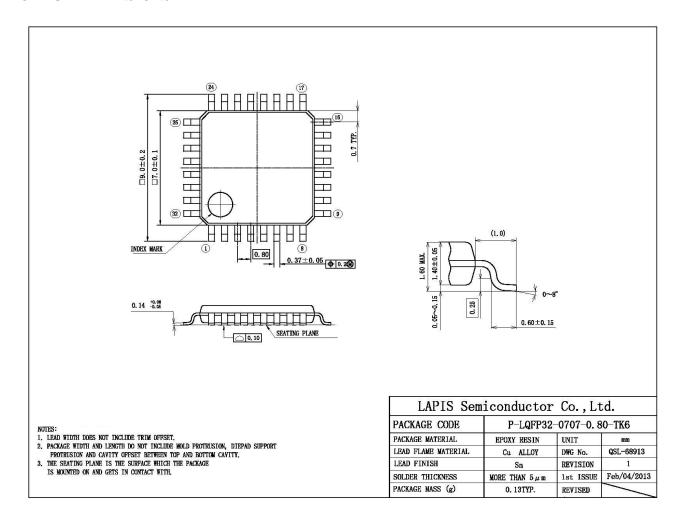


Figure 3 LQFP32

Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact ROHM's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

# **REVISION HISTORY**

		Pa	ige	
Document No.	Date	Previous Edition	Current Edition	Description
FEDL610Q772-01	2015.12.11	_	_	Final Edition issued

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